Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



**Top Material: Al**

**Backside Material: Si Ni**

**Bond Pad Size: .0034” X .0034”**

**Backside Potential:**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .047” X .050” DATE: 9/9/21**

**MFG: TEXAS INSTRUMENTS THICKNESS .025” P/N: 55453**

**DG 10.1.2**

#### Rev B, 7/19/02